

# SOT199

plastic single-ended package; heatsink mounted; 1 mounting hole; 3 lead TO-247 "full pack"

8 February 2016

Package information

## 1. Package summary

Terminal position code	S (single)
Package type descriptive code	TO-247F
Package type industry code	TO-247F
Package style descriptive code	SFM (single-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
JEDEC package outline code	3-lead TO-247F
Mounting method type	H (heatsink mount)
Issue date	13-9-1999

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		20.5	-	21	21.5	mm
E	package width		14.7	-	15	15.3	mm
A	seated height		4.8	-	5	5.2	mm
e	nominal pitch		-	-	2.54	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	3	-	



2. Package outline

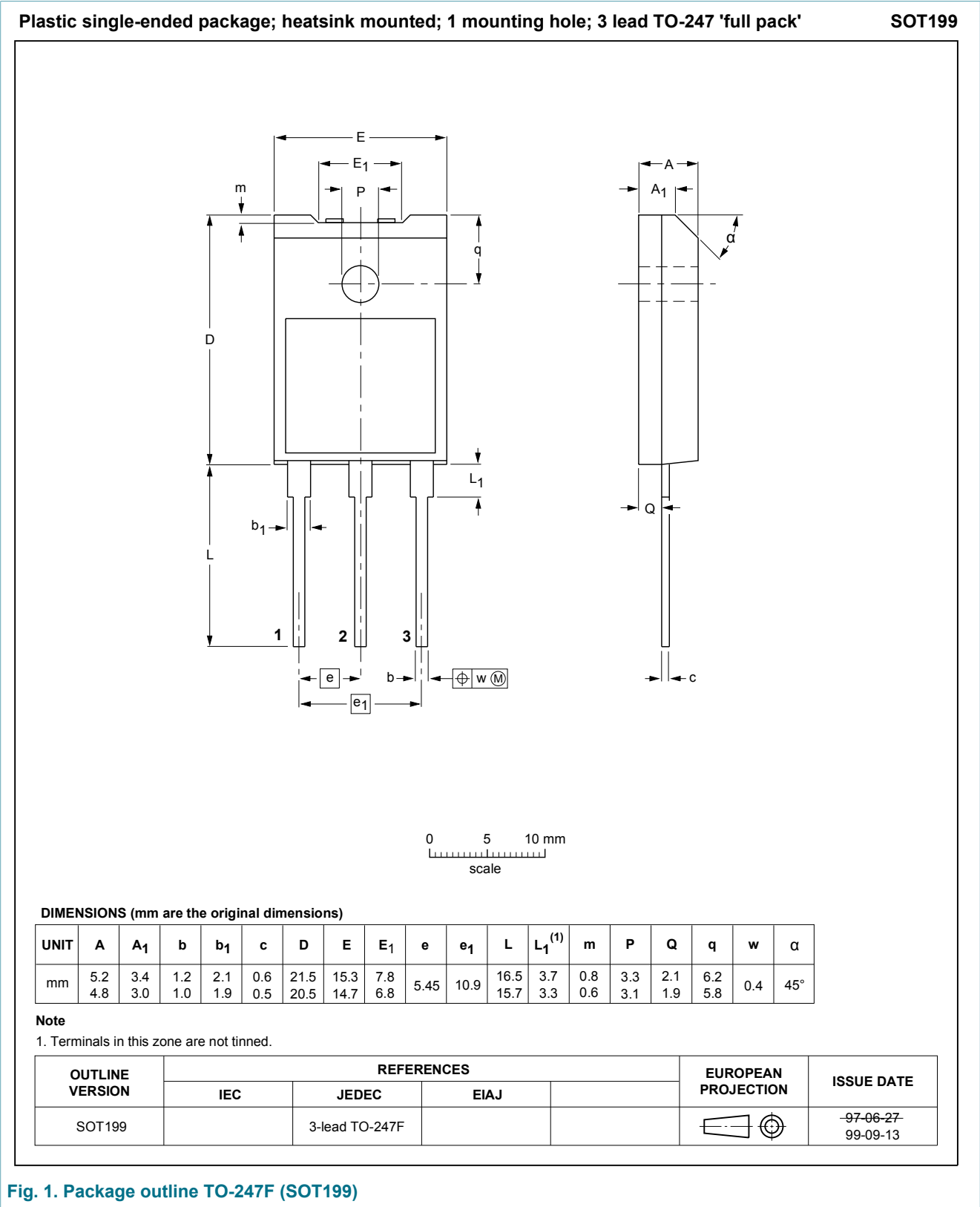


Fig. 1. Package outline TO-247F (SOT199)

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### 3. Legal information

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